

# SEMITRANS<sup>®</sup> 3

### **Trench IGBT Modules**

#### SKM 400GB176D SKM 400GAL176D

#### Features

- Homogeneous Si
- Trench = Trenchgate technology
- V<sub>CE(sat)</sub> with positive temperature coefficient
- High short circuit capability, self limiting to 6 x I<sub>C</sub>

#### **Typical Applications\***

- AC inverter drives
- mains 575 750 V AC
- Public transport (auxiliary syst.)
- Wind power

GB	GAL	

Absolut	te Maximum Ratings	T <sub>case</sub> =	= 25°C, unless otherwise s	pecified
Symbol Conditions			Values	Units
IGBT				
V <sub>CES</sub>	T <sub>j</sub> = 25 °C		1700	V
I <sub>C</sub>	T <sub>j</sub> = 150 °C	T <sub>c</sub> = 25 °C	430	Α
		T <sub>c</sub> = 80 °C	310	А
I <sub>CRM</sub>	I <sub>CRM</sub> =2xI <sub>Cnom</sub>		600	А
V <sub>GES</sub>			± 20	V
t <sub>psc</sub>	$V_{CC}$ = 1200 V; $V_{GE} \leq$ 20 V;	T <sub>j</sub> = 125 °C	10	μs
	V <sub>CES</sub> < 1700 V			
Inverse			_	_
I <sub>F</sub>	T <sub>j</sub> = 150 °C	T <sub>c</sub> = 25 °C	440	A
		T <sub>c</sub> = 80 °C	300	А
I <sub>FRM</sub>	I <sub>FRM</sub> =2xI <sub>Fnom</sub>		600	А
I <sub>FSM</sub>	t <sub>p</sub> = 10 ms; sin.	T <sub>j</sub> = 150 °C	2200	А
Freewh	eeling Diode			•
I <sub>F</sub>	T <sub>j</sub> = 150 °C	T <sub>case</sub> = 25 °C	440	Α
		T <sub>case</sub> = 80 °C	300	Α
I <sub>FRM</sub>	I <sub>FRM</sub> =2xI <sub>Fnom</sub>		600	А
I <sub>FSM</sub>	t <sub>p</sub> = 10 ms; sin.	T <sub>j</sub> = 150 °C	2200	Α
Module				•
I <sub>t(RMS)</sub>			500	А
T <sub>vj</sub>			- 40 + 150	°C
T <sub>stg</sub>			- 40 + 125	°C
V <sub>isol</sub>	AC, 1 min.		4000	V

Characteristics T <sub>case</sub> =			25°C, unless otherwise specified			
Symbol	Conditions		min.	typ.	max.	Units
IGBT						
V <sub>GE(th)</sub>	$V_{GE} = V_{CE}, I_C = 12 \text{ mA}$		5,2	5,8	6,4	V
I <sub>CES</sub>	$V_{GE}$ = 0 V, $V_{CE}$ = $V_{CES}$	T <sub>j</sub> = 25 °C			4	mA
V <sub>CE0</sub>		T <sub>j</sub> = 25 °C		1	1,2	V
		T <sub>j</sub> = 125 °C		0,9	1,1	V
r <sub>CE</sub>	V <sub>GE</sub> = 15 V	T <sub>j</sub> = 25°C		3,3	4,2	mΩ
		T <sub>j</sub> = 125°C		5,2	6	mΩ
V <sub>CE(sat)</sub>	I <sub>Cnom</sub> = 300 A, V <sub>GE</sub> = 15 V	T <sub>j</sub> = 25°C <sub>chiplev.</sub>		2	2,4	V
		T <sub>j</sub> = 125°C <sub>chiplev.</sub>		2,45	2,9	V
C <sub>ies</sub>				19,8		nF
C <sub>oes</sub>	V <sub>CE</sub> = 25, V <sub>GE</sub> = 0 V	f = 1 MHz		1,1		nF
C <sub>res</sub>				0,88		nF
Q <sub>G</sub>	V <sub>GE</sub> = -8V+15V			2500		nC
t <sub>d(on)</sub>				330		ns
t <sub>r</sub>	$R_{Gon} = 4 \Omega$	V <sub>CC</sub> = 1200V		55		ns
É <sub>on</sub>		I <sub>C</sub> = 300A		170		mJ
t <sub>d(off)</sub>	$R_{Goff} = 4 \Omega$	T <sub>j</sub> = 125 °C		880		ns
t <sub>f</sub>		V <sub>GE</sub> = ± 15V		145		ns
E <sub>off</sub>				118		mJ
R <sub>th(j-c)</sub>	per IGBT				0,075	K/W

#### 28-06-2010 GIL



SEMITRANS<sup>®</sup> 3

#### Trench IGBT Modules

#### SKM 400GB176D SKM 400GAL176D

#### Features

- Homogeneous Si
- Trench = Trenchgate technology
- V<sub>CE(sat)</sub> with positive temperature coefficient
- High short circuit capability, self limiting to 6 x I<sub>C</sub>

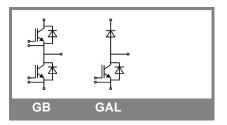
#### **Typical Applications\***

- AC inverter drives
- mains 575 750 V AC
- Public transport (auxiliary syst.)
- Wind power

Characte						
Symbol	Conditions		min.	typ.	max.	Units
Inverse D						
$V_F = V_{EC}$	$I_{Fnom}$ = 300 A; $V_{GE}$ = 0 V			1,7	1,9	V
		$T_j = 125 \ ^\circ C_{chiplev.}$ $T_j = 25 \ ^\circ C$		1,8	2	V
V <sub>F0</sub>				1,2	1,4	V
		T <sub>j</sub> = 125 °C		0,9	1,1	V
r <sub>F</sub>		T <sub>j</sub> = 25 °C		1,7	1,7	mΩ
		T <sub>j</sub> = 125 °C		3	3	mΩ
I <sub>RRM</sub>	I <sub>F</sub> = 300 A	T <sub>j</sub> = 125 °C		418		А
Q <sub>rr</sub>	di/dt = 5800 A/µs			117		μC
E <sub>rr</sub>	$V_{GE}$ = -15 V; $V_{CC}$ = 1200 V	/		78		mJ
R <sub>th(j-c)D</sub>	per diode				0,125	K/W
FWD						•
V <sub>F</sub> = V <sub>EC</sub>	$I_{Fnom}$ = 300 A; $V_{GE}$ = 0 V	T <sub>j</sub> = 25 °C <sub>chiplev.</sub>		1,7	1,9	V
		$T_j = 125 \ ^\circ C_{chiplev.}$ $T_j = 25 \ ^\circ C$		1,8	2	V
V <sub>F0</sub>		T <sub>j</sub> = 25 °C		1,2	1,4	V
		T <sub>j</sub> = 125 °C		0,9	1,1	V
r <sub>F</sub>		T <sub>j</sub> = 25 °C		1,7	1,7	V
		T <sub>j</sub> = 125 °C		3	3	V
I <sub>RRM</sub>	I <sub>F</sub> = 300 A	T <sub>j</sub> = 125 °C		418		А
Q <sub>rr</sub>	di/dt = 5800 A/µs			117		μC
Err	$V_{GE}$ = -15 V; $V_{CC}$ = 1200 V	/		78		mJ
R <sub>th(j-c)FD</sub>	per diode				0,125	K/W
Module						
L <sub>CE</sub>				15	20	nH
R <sub>CC'+EE'</sub>	res., terminal-chip	T <sub>case</sub> = 25 °C		0,35		mΩ
		T <sub>case</sub> = 125 °C		0,5		mΩ
R <sub>th(c-s)</sub>	per module				0,038	K/W
M <sub>s</sub>	to heat sink M6		3		5	Nm
M <sub>t</sub>	to terminals M6		2,5		5	Nm
w					325	g

This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

\* The specifications of our components may not be considered as an assurance of component characteristics. Components have to be tested for the respective application. Adjustments may be necessary. The use of SEMIKRON products in life support appliances and systems is subject to prior specification and written approval by SEMIKRON. We therefore strongly recommend prior consultation of our personal.





Z<sub>th</sub> Symbol

Z Rith(j-c)I Conditions

i = 1

# SEMITRANS<sup>®</sup> 3

#### Trench IGBT Modules

#### R i = 2 18 R i = 3 4,6 R<sub>i</sub> i = 4 0,4 0,0569 tau, i = 1 i = 2 0,0122 tau<sub>i</sub> 0,002 tau<sub>i</sub> i = 3 tau<sub>i</sub> i = 4 0.02 Z <sub>Ri</sub>th(j-c)D i = 1 85 R i = 2 28 R<sub>i</sub> i = 3 10,5 R<sub>i</sub> i = 4 1,5 0,054 tau<sub>i</sub> i = 1 0,0075 tau, i = 2 tau<sub>i</sub> i = 3 0,0018 i = 4 0,0002 tau,

Values

52

Units

mk/W

mk/W

mk/W

mk/W

s

s

s

s

mk/W

mk/W

mk/W

mk/W

s

s

s

s

#### Features

Homogeneous Si

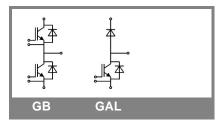
SKM 400GB176D

**SKM 400GAL176D** 

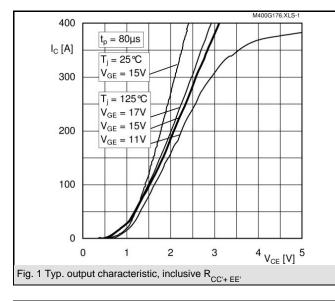
- Trench = Trenchgate technology
- V<sub>CE(sat)</sub> with positive temperature coefficient
- High short circuit capability, self limiting to 6 x I<sub>C</sub>

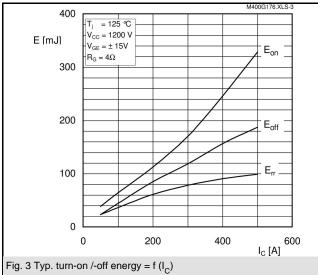
#### **Typical Applications\***

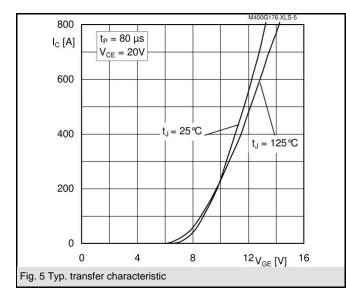
- AC inverter drives
- mains 575 750 V AC
- Public transport (auxiliary syst.)
- Wind power

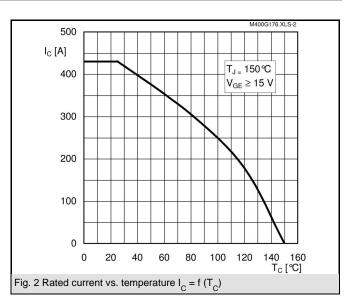


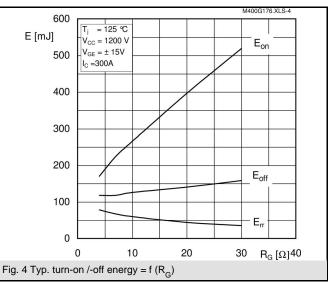
3

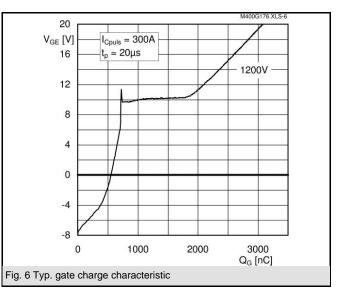




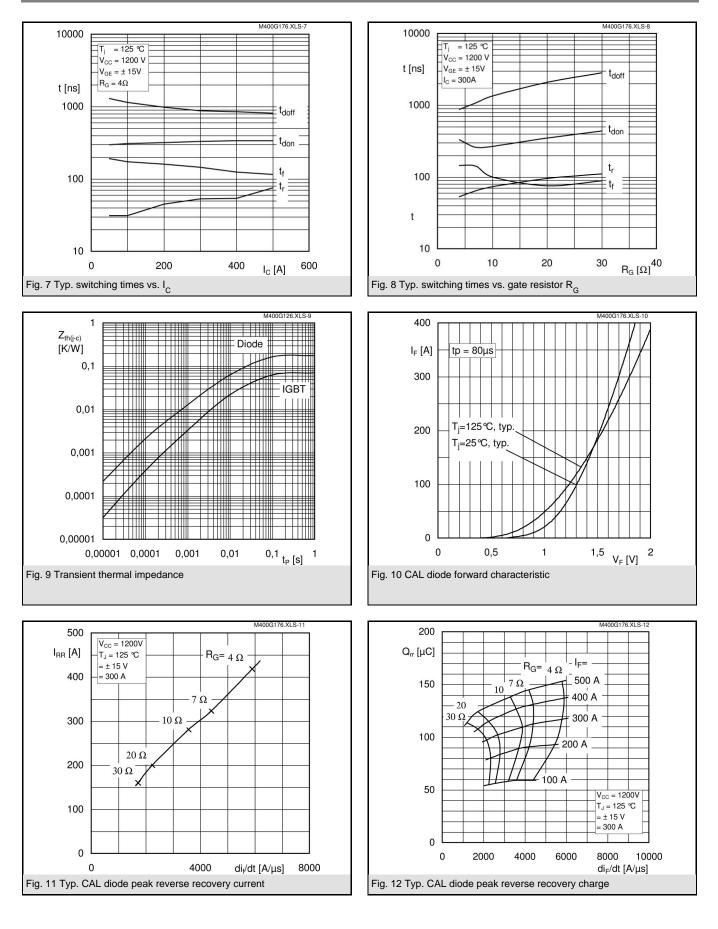








4



28-06-2010 GIL

5

